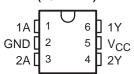
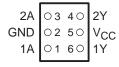
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- **Available in the Texas Instruments** NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max tpd of 5.4 ns at 3.3 V
- Low Power Consumption, 10-µA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Typical V_{OI P} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- **I**off Feature Supports Partial-Power-Down **Mode Operation**
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW)



YEA, YEP, YZA, OR YZP PACKAGE (BOTTOM VIEW)



description/ordering information

This dual Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

ORDERING INFORMATION

TA	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
−40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA		SN74LVC2G14YEAR	
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)	Reel of 3000	SN74LVC2G14YZAR	0.5
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		SN74LVC2G14YEPR	CF_
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC2G14YZPR	
	207 (207 22) PP) (Reel of 3000	SN74LVC2G14DBVR	044
	SOT (SOT-23) – DBV	Reel of 250	SN74LVC2G14DBVT	C14_
	SOT (SC-70) - DCK	Reel of 3000	SN74LVC2G14DCKR	CF
	301 (30-70) - DCK	Reel of 250	SN74LVC2G14DCKT	01-

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SCES200J - APRIL 1999 - REVISED SEPTEMBER 2003

description/ordering information (continued)

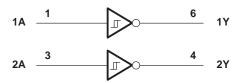
The SN74LVC2G14 contains two inverters and performs the Boolean function $Y = \overline{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	
Voltage range applied to any output in the high-impedance or power-off state, V _O (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	–0.5 V to V_{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DBV package	165°C/W
DCK package	
YEA/YZA package	143°C/W
YEP/YZP package	123°C/W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LVC2G14 DUAL SCHMITT-TRIGGER INVERTER

SCES200J - APRIL 1999 - REVISED SEPTEMBER 2003

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
.,	Ouranteersteens	Operating	1.65	5.5	
VCC	Supply voltage Data retention only		1.5		V
٧ı	Input voltage		0	5.5	V
٧o	Output voltage		0	Vcc	V
		V _{CC} = 1.65 V		-4	
	High-level output current	V _{CC} = 2.3 V		-8	
lOH		V 0V		-16	mA
		VCC = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
	Low-level output current $ V_{CC} = 2.3 \text{ V} $ $ V_{CC} = 3 \text{ V} $		8		
loL		V 0V		16	mA
		ACC = 3 A		24	
	V _{CC} = 4.5 V			32	
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SCES200J - APRIL 1999 - REVISED SEPTEMBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYPT MAX	UNIT	
		1.65 V	0.7	1.4		
V _{T+}		2.3 V	1	1.7		
Positive-going input		3 V	1.3	2.2	V	
threshold voltage		4.5 V	1.9	3.1		
		5.5 V	2.2	3.7		
		1.65 V	0.3	0.7		
V _T _		2.3 V	0.4	1		
Negative-going input		3 V	0.6	1.3	V	
threshold voltage		4.5 V	1.1	2		
		5.5 V	1.4	2.5		
		1.65 V	0.3	0.8		
ΔVΤ		2.3 V	0.4	0.9		
Hysteresis		3 V	0.4	1.1	V	
$(V_{T+} - V_{T-})$		4.5 V	0.6	1.3		
		5.5 V	0.7	1.4		
	I _{OH} = -100 μA	1.65 V to 4.5 V	V _{CC} -0.1			
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
.,	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		.,	
VOH	I _{OH} = -16 mA	3 V	2.4		V	
	I _{OH} = -24 mA	3 V	2.3			
	I _{OH} = -32 mA	4.5 V	3.8			
	I _{OL} = 100 μA	1.65 V to 4.5 V		0.1		
	I _{OL} = 4 mA	1.65 V		0.45		
.,	I _{OL} = 8 mA	2.3 V		0.3	.,	
V _{OL}	I _{OL} = 16 mA	3 V		0.4	V	
	I _{OL} = 24 mA	3 V		0.55		
	I _{OL} = 32 mA	4.5 V		0.55		
I _I A input	V _I = 5.5 V or GND	0 to 5.5 V		±5	μΑ	
l _{off}	V _I or V _O = 5.5 V	0		±10	μΑ	
ICC	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V		10	μΑ	
ΔlCC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V		500	μΑ	
C _i	$V_I = V_{CC}$ or GND	3.3 V		4	pF	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} =		UNIT						
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A	Y	3.9	9.5	1.9	5.7	2	5.4	1.5	4.3	ns



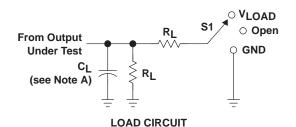
SN74LVC2G14 DUAL SCHMITT-TRIGGER INVERTER

SCES200J - APRIL 1999 - REVISED SEPTEMBER 2003

operating characteristics, $T_A = 25^{\circ}C$

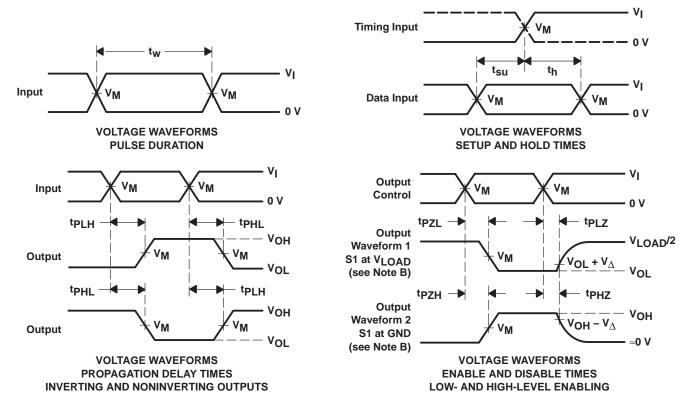
PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	LINUT	
	FARAMETER	TEST CONDITIONS	TYP	TYP	TYP	TYP	UNIT	
C _{pd}	Power dissipation capacitance	f = 10 MHz	16	17	18	21	pF	

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
^t PHZ ^{/t} PZH	GND

W	INPUTS			V	6	D.	V
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_I includes probe and jig capacitance.

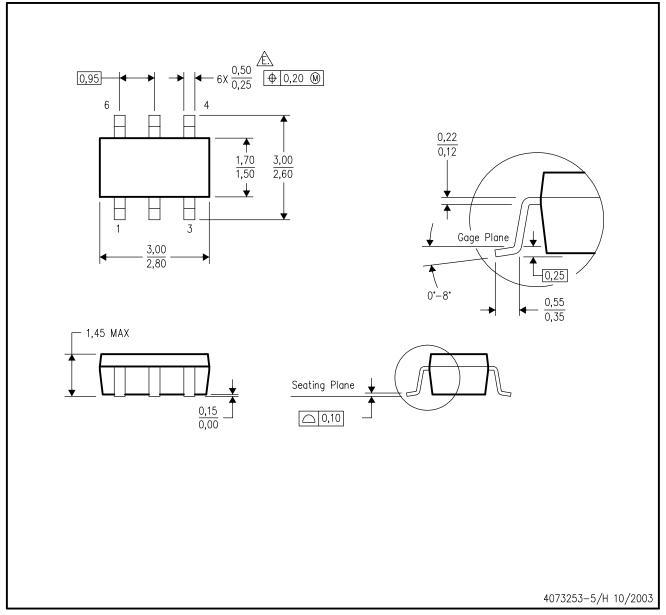
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



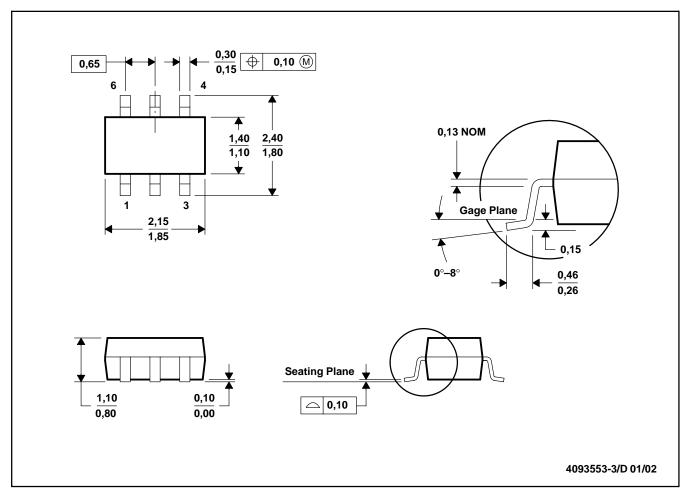
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

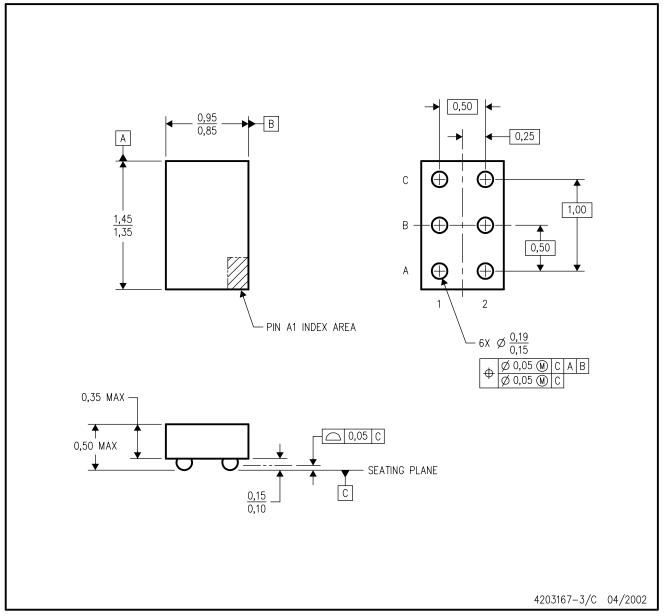


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

YEA (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

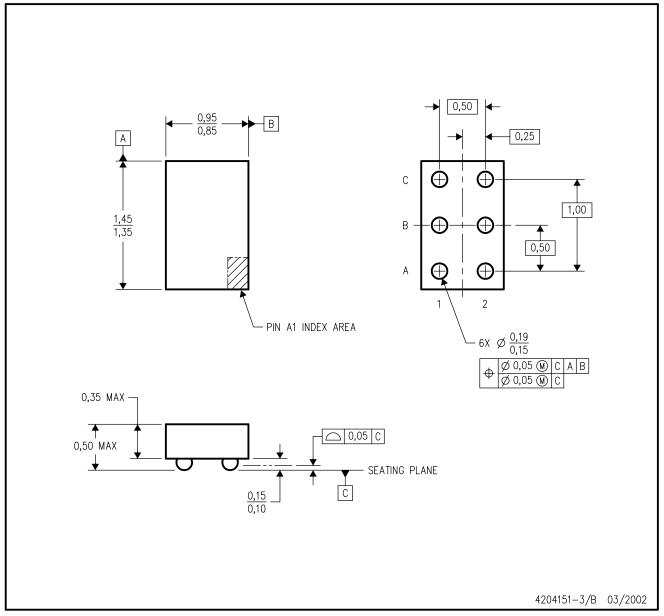
- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 6 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

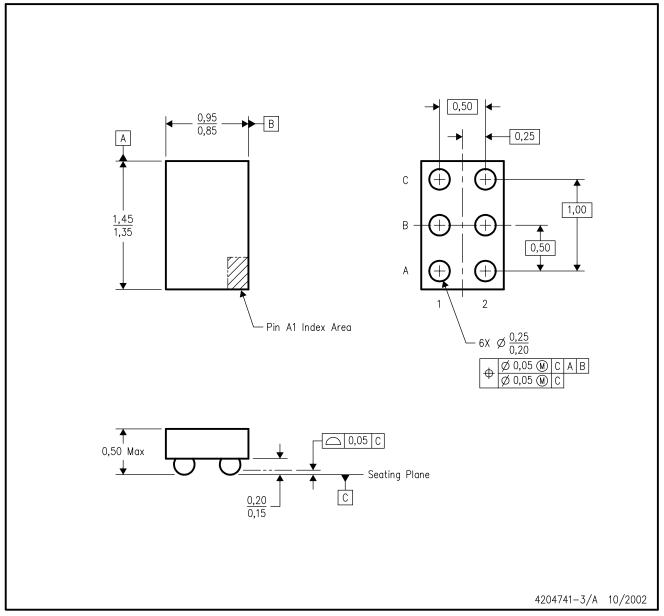
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 6 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

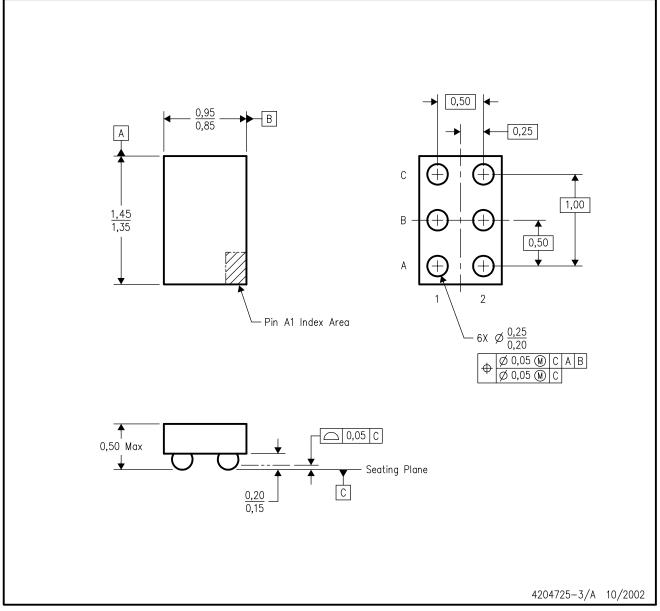
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



YEP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 6 YZP package (drawing 4204741) for lead-free.

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